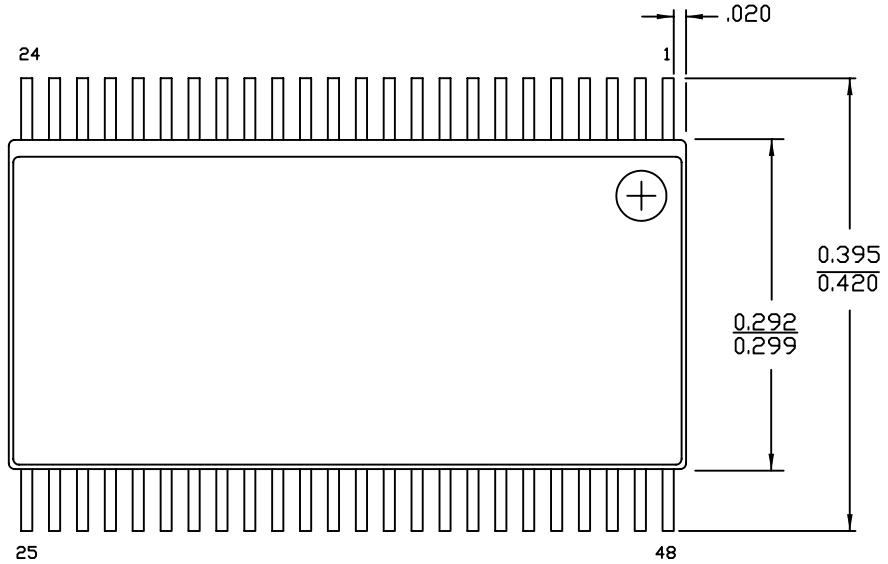
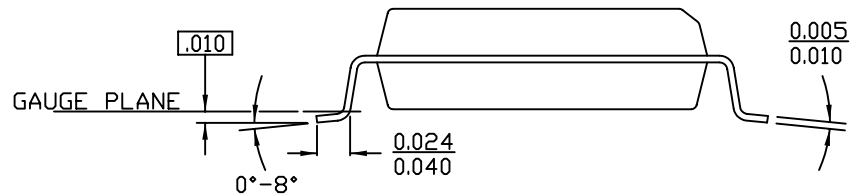
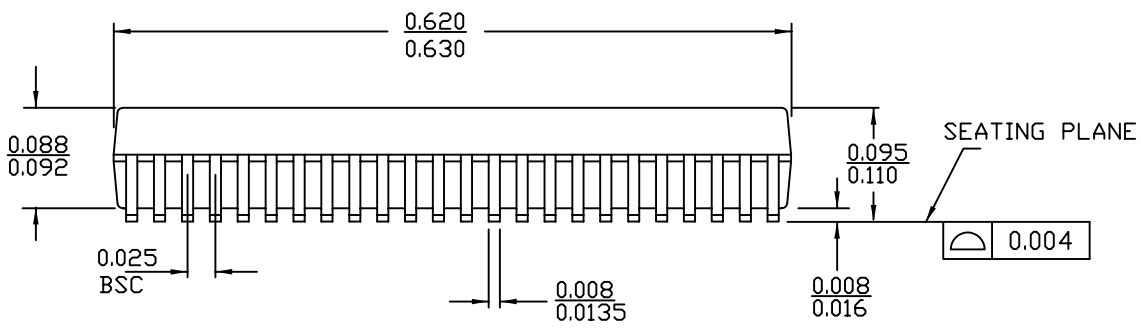


48 Lead Shrunk Small Outline Package 048

REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	1043	NEW RELEASE	11/11/94	N/A
1	-	*A	44327	CHG. LEAD SPREAD PKG. WIDTH FROM 0.400/0.410 TO 0.395/0.420	08/28/96	N/A
1	-	*B	49409	CHG. TITLE	06/11/97	N/A
1	-	*C	100360	ADD LEAD THICKNESS DIM.	04/28/00	N/A
1	-	*D	2851411	Changed template, & title from 48LD (300 MIL) SSOP PKG OUTLINE to PACKAGE OUTLINE, 48LD SSOP 300 MILS 0483.	01/15/10	QAD
1	-	*E	3352992	UPDATE SPEC FOR SUNSET REVIEW, NO CHANGE.	08/24/11	QAD
1	-	*F	3722534	ADDED "PKG WEIGHT: REFER TO PMDD SPEC."	08/24/12	QAD



DIMENSIONS IN INCHES MIN.
MAX.
PKG. WEIGHT: REFER TO PMDD SPEC.



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UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ARE: DECIMALS .XX ± 0.05 .XXX ± .0008 .XXXX ± .00135 ANGLES ± 1°	DESIGNED BY	HTN	DATE	04/28/00	
	DRAWN BY	HTN	DATE	04/28/00	
	CHECKED BY	EDCA	DATE	08/24/12	
	APPROVED BY	ZZQ	DATE	08/24/12	
MATERIAL	N/A	APPROVED BY	QAD	DATE	08/24/12
FINISH	N/A	APPROVED BY	CMG	DATE	08/24/12



TITLE				PACKAGE OUTLINE, 48LD SSOP 300 MILS 0483			
SIZE	PART NO.	DWG NO.	REV				
A	0483	51-85061	*F				
SCALED TO FIT		N/A		SHEET 1		OF 1	